

G2300**N-CHANNEL ENHANCEMENT MODE POWER MOSFET**

BV _{DSS}	20V
R _{DSON}	28mΩ
I _D	6A

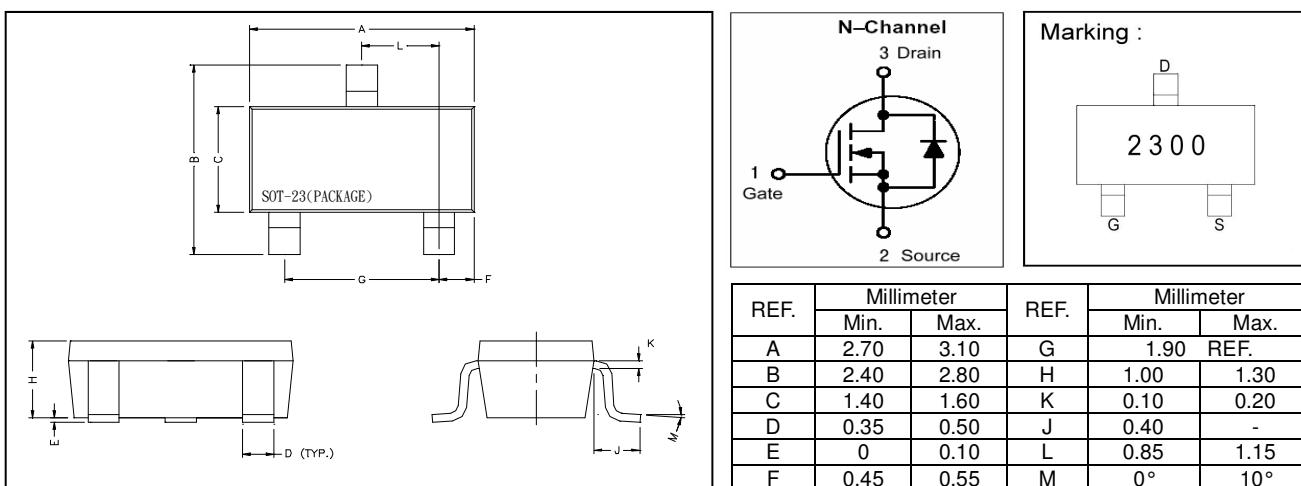
Description

The G2300 provide the designer with best combination of fast switching, low on-resistance and cost-effectiveness.

The G2300 is universally used for all commercial-industrial surface mount applications.

Features

- *Low on-resistance
- *Capable of 2.5V gate drive
- *Small Package Outline

Package Dimensions**Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±8	V
Continuous Drain Current ³	I _D @ T _A =25°C	6	A
Continuous Drain Current ³	I _D @ T _A =70°C	4.8	A
Pulsed Drain Current ^{1,2}	I _{DM}	20	A
Power Dissipation	P _D @ T _A =25°C	1.25	W
Linear Derating Factor		0.01	W/°C
Operating Junction and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-ambient ³ Max.	R _{thj-a}	100	°C/W

Electrical Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	20	-	-	V	$\text{V}_{\text{GS}}=0, \text{I}_D=250\mu\text{A}$
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}} / \Delta T_j$	-	0.1	-	V/ $^\circ\text{C}$	Reference to 25°C , $\text{I}_D=1\text{mA}$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	0.5	-	1.0	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$\text{V}_{\text{GS}}= \pm 8\text{V}$
Drain-Source Leakage Current($T_j=25^\circ\text{C}$)	I_{DSS}	-	-	1	uA	$\text{V}_{\text{DS}}=20\text{V}, \text{V}_{\text{GS}}=0$
Drain-Source Leakage Current($T_j=70^\circ\text{C}$)		-	-	25	uA	$\text{V}_{\text{DS}}=16\text{V}, \text{V}_{\text{GS}}=0$
Static Drain-Source On-Resistance ²	$\text{R}_{\text{DS}(\text{ON})}$	-	-	28	m Ω	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=6\text{A}$
		-	-	38		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=5.2\text{A}$
Total Gate Charge ²	Q_g	-	10	-	nC	$\text{I}_D=6\text{A}$ $\text{V}_{\text{DS}}=10\text{V}$ $\text{V}_{\text{GS}}=4.5\text{V}$
Gate-Source Charge	Q_{gs}	-	3.6	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	2	-		
Turn-on Delay Time ²	$\text{T}_{\text{d}(\text{on})}$	-	8	-		
Rise Time	T_r	-	6	-	ns	$\text{V}_{\text{DD}}=10\text{V}$ $\text{I}_D=1\text{A}$ $\text{V}_{\text{GS}}=4.5\text{V}$ $\text{R}_G=0.2\Omega$
Turn-off Delay Time	$\text{T}_{\text{d}(\text{off})}$	-	19	-		
Fall Time	T_f	-	7	-		
Input Capacitance	C_{iss}	-	550	-		
Output Capacitance	C_{oss}	-	120	-	pF	$\text{V}_{\text{GS}}=0\text{V}$ $\text{V}_{\text{DS}}=15\text{V}$ $f=1.0\text{MHz}$
Reverse Transfer Capacitance	C_{rss}	-	80	-		

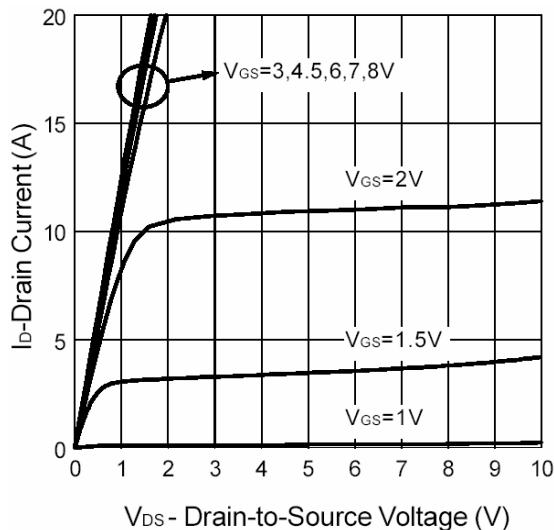
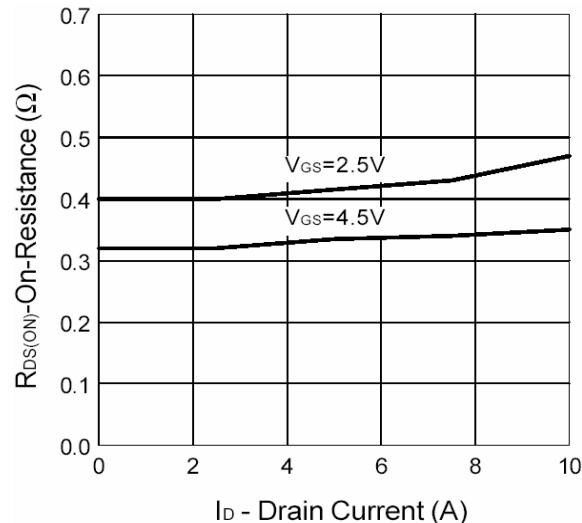
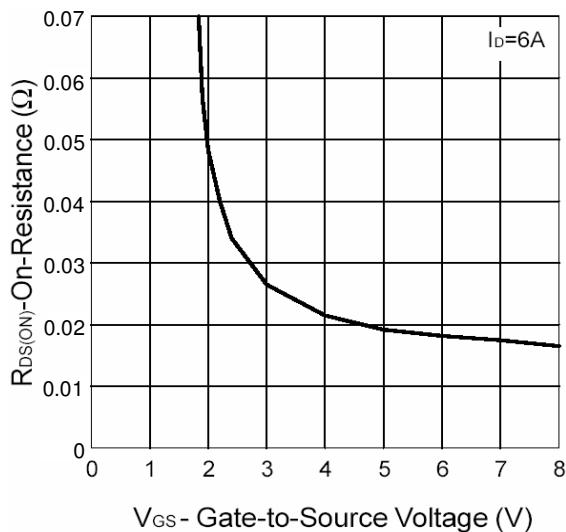
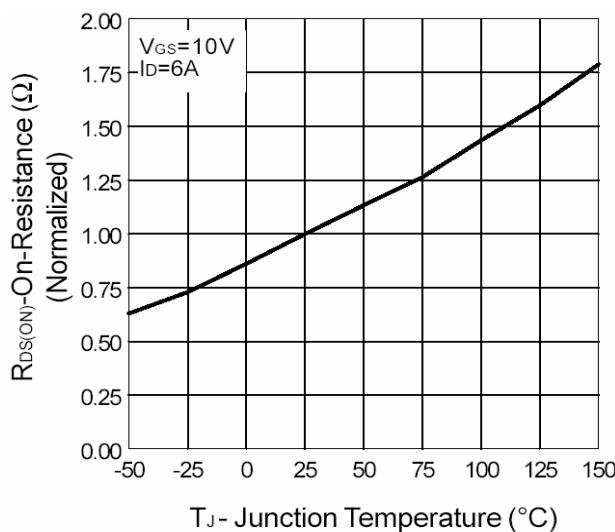
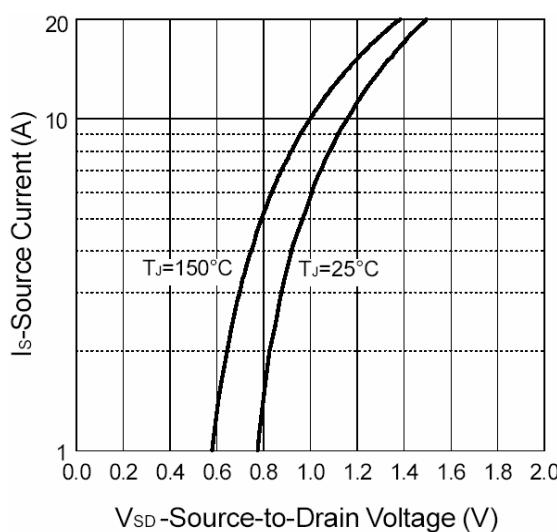
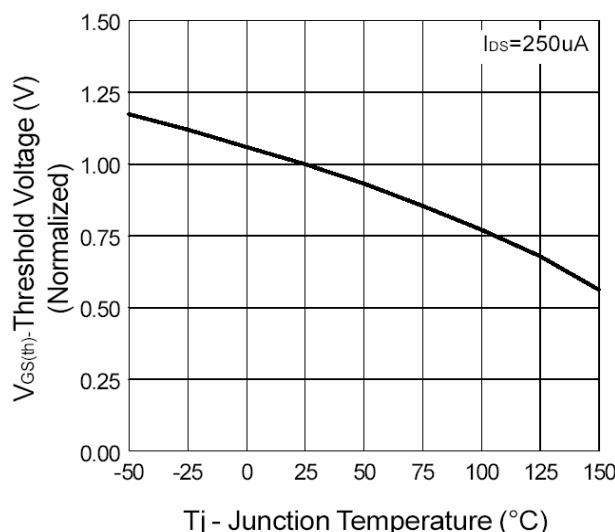
Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V_{SD}	-	0.7	1.3	V	$\text{I}_S=1.25\text{A}, \text{V}_{\text{GS}}=0\text{V}$

Notes: 1. Pulse width limited by Max. junction temperature.

2. Pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

3. Surface mounted on FR4 board, $t \leq 10\text{sec}$.

Characteristics Curve**Fig 1. Typical Output Characteristics****Fig 2. On-Resistance v.s. Drain Current****Fig 3. On-Resistance v.s. Gate Voltage****Fig 4. Normalized On-Resistance v.s. Junction Temperature****Fig 5. Source-Drain Diode Forward Voltage****Fig 6. Gate Threshold Voltage v.s. Junction Temperature**

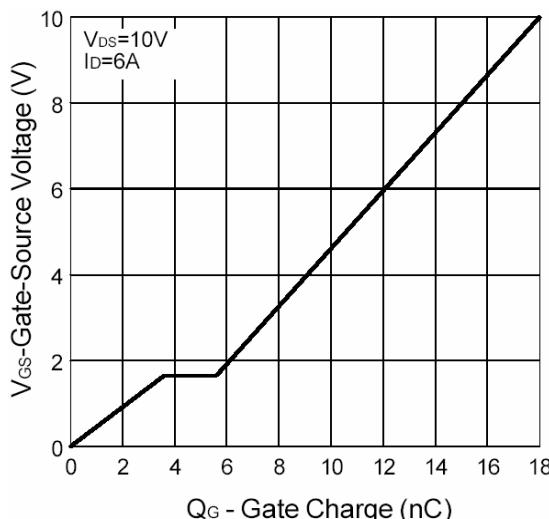


Fig 7. Gate Charge Characteristics

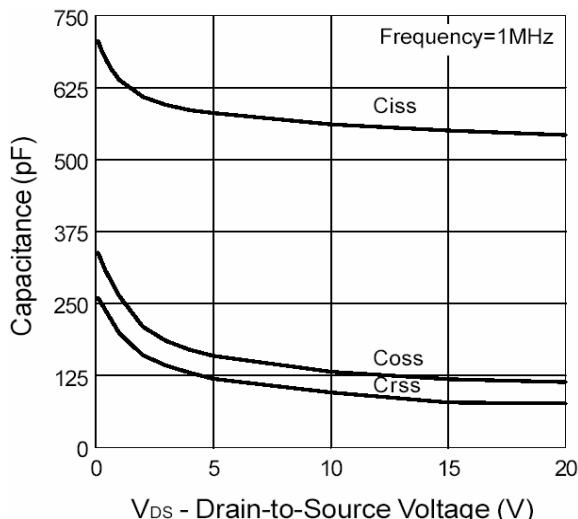


Fig 8. Typical Capacitance Characteristics

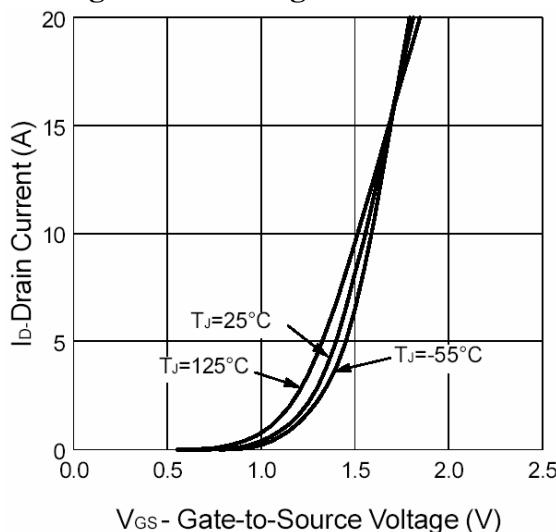


Fig 9. Transfer Characteristics

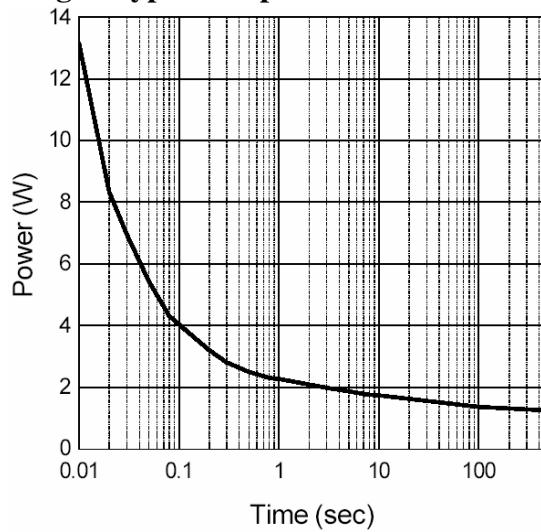


Fig 10. Single Pulse Power

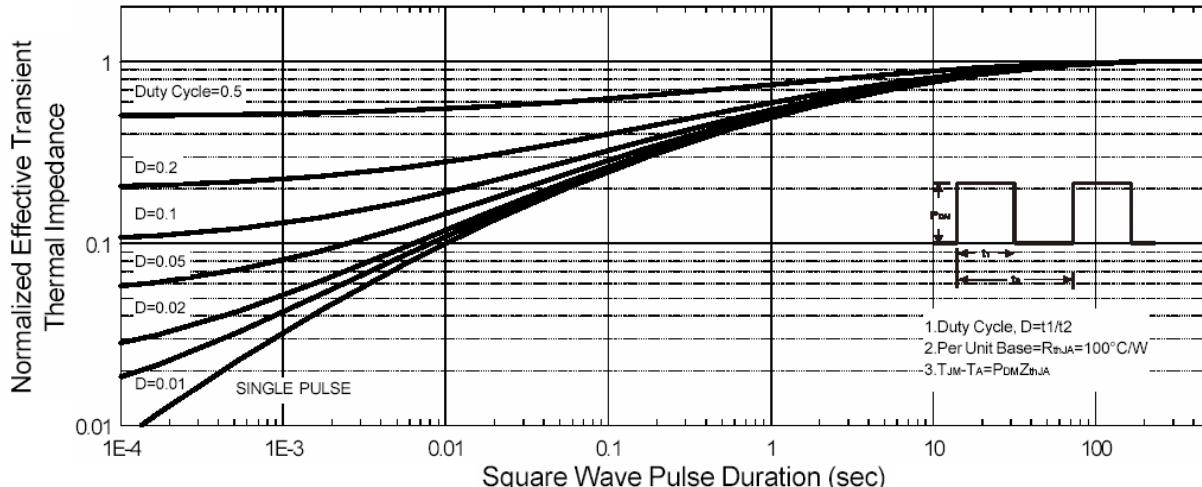


Fig 11. Normalized Thermal Transient Impedance, Junction to Ambient

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Head Office And Factory:

- Taiwan:** No. 17-1 Tatung Rd. Fu Kou Hsin-Chu Industrial Park, Hsin-Chu, Taiwan, R. O. C.
TEL : 886-3-597-7061 FAX : 886-3-597-9220, 597-0785
- China:** (201203) No.255, Jiang-Jiang Tsai-Lueng RD. , Pu-Dung-Hsin District, Shang-Hai City, China
TEL : 86-21-5895-7671 ~ 4 FAX : 86-21-38950165